US 20230230859A1

(19) **United States**

(12) **Patent Application Publication** (10) **Pub. No.: US 2023/0230859 A1**

TANNOUS et al. (43) **Pub. Date: Jul. 20, 2023**

(54) **BATCH THERMAL PROCESS CHAMBER**

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(21) Appl. No.: **17/919,911**

(22) PCT Filed: **Jul. 12, 2021**

(86) PCT No.: **PCT/US2021/041287**

§ 371 (c)(1),
(2) Date: **Oct. 19, 2022**

(30) **Foreign Application Priority Data**

Aug. 3, 2020 (IN) 202041033208

Publication Classification

(51) **Int. Cl.**

H01L 21/67	(2006.01)
H01L 21/687	(2006.01)
H05B 3/00	(2006.01)

(52) **U.S. Cl.**

CPC .. ***H01L 21/67115*** (2013.01); ***H01L 21/67184*** (2013.01); ***H01L 21/6719*** (2013.01); ***H01L 21/68771*** (2013.01); ***H05B 3/0047*** (2013.01)

(57) **ABSTRACT**

A batch processing chamber and a process kit for use therein are provided. The process kit includes an outer liner having an upper outer liner and a lower outer liner, an inner liner, and a top plate and a bottom plate attached to an inner surface of the inner liner. The top plate and the bottom plate form an enclosure together with the inner liner, and a cassette is disposed within the enclosure. The cassette including shelves configured to retain a plurality of substrates thereon. The inner liner has inlet openings disposed on an injection side of the inner liner and configured to be in fluid communication with a gas injection assembly of a processing chamber, and outlet openings disposed on an exhaust side of the inner liner and configured to be in fluid communication with a gas exhaust assembly of the processing chamber. The inner surfaces of the enclosure comprise material configured to cause black-body radiation within the enclosure.